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Optical Probe Development and Validation for Next Generation Process Nodes"; "Session 3: Packaging and Assembly Level FA I"; "3DIC Fault Isolation Using the OBIRCH Approach"; "Improving Wire Sweep Performance by Measuring Degree of Cure of Epoxy Mold Compounds"; "Use of Lock-In Thermography for Non-Destructive 3D Defect Localization on System in Package and Stacked-Die Technology"

"Quantitative Phase Shift Analysis for 3D Defect Localization Using Lock-in Thermography""Failure Analysis of Flip Chip C4 Package Using Focused Ion Beam Milling Technique"; "Session 4: Test and Diagnostics"; "Layout-aware Diagnosis Leads to Efficient and Effective Physical Failure Analysis"; "Device Selection for Failure Analysis of Chain Fails Using Diagnosis Driven Yield Analysis"; "Debugging an Invisible Flaky Scan Chain Defect"; "Diagnose Compound Hold Time Faults Caused by Spot Delay Defects at Clock Tree"; "Session 5: Defect Characterization and Metrology"

"A Comprehensive Analysis Methodology for Gate Oxide Integrity Failure Using Combined FA Techniques""Al Bondpads, Halogens, and an ESCA-based Search for the Invisible Cause of Poor Throughput at Wafer Probe"; "Whisker Formation in Copper Electroplating"; "Comprehensive nano-structural approach of SSRM nanocontact on silicon through TEM-STEM study"; "Highly Automated Transmission Electron Microscopy Tomography for Defect Understanding"; "Transmission Electron Microscopy Characterization of FinFET a€? Understanding the 3D Structure by 2D Imaging Technique"

"Session 6: Photon Based Fault Isolation Techniques"

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